LBI-38163B



Mobile Communications

EDACS[®] 900 MHz TRUNKED RECEIVER 19D902120G1



Ericsson GE Mobile Communications Inc. Mountain View Road Lynchburg Virginia 24502

Maintenance Manual

Printed in U.S.A

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SPECIFICATIONS*

896.0125 — 900.9875 MHz Frequency Range Audio Output AUDIO PA 2 Watts at 8 Ohms 1 Vrms @ 1.5 khz Deviation with 1 kHz modulation Vol/ Squelch Hi Selectivity 75 dB adjacent channel Spurious Response - 80 dB minimum Image All Other - 90 dB minimum Intermodulation - 65 dB Adjacent Channel Alt. Channel and Beyond - 80 dB 12 dB SINAD - 120 dBm typical Rated Output Audio Board 19D902181G1 2 Watts Audio Board 19D902093G1 5 Watts Distortion Less than 5% 0.05 PPM (high stability reference) Frequency Stability AM Rejection - 26 dB minimum Hum and Noise - 40 dB

*These specifications are intended primarily for use by service personnel. Refer to the appropriate Specification Sheet for complete specifications.

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DESCRIPTION

These receivers are double conversion, superheterodyne, single frequency FM receivers for operation in trunked repeater systems. The receiver utilizes monolithic crystal filters between the IF gain stages to provide the selectivity and intermodulation required to meet or exceed all EIA specifications for trunked receivers.

The receiver consists of the receiver board and audio board, with audio and control functions as well as supply voltages applied through the system board.

NOTE

The trunked 900 MHz receivers may be equipped with either audio board 19D02181G1 or 19D902093G1, as the boards are directly interchangeable. In earlier model receivers, audio board 19D902093G1 was used. In later model receivers, audio board 19D902181G1 is used. Service information for both audio boards is provided in this Maintenance Manual.

CIRCUIT ANALYSIS

RECEIVER BOARD

The receiver board consists of the RF amplifier, mixer and 1st IF, 2nd IF and audio stages, and a synthesizer circuit. The receiver board uses a combination of crystal and ceramic bandpass filters for good intermodulation and desensitization characteristics. A Block Diagram of the receiver board is shown in Figure 1.

RF Front End

RF signal input from the antenna is applied to the receiver board through J1. The 896-901 MHz input is coupled through broadband ceramic filter FL1 to RF amplifier, U1. Amplifier U1 provides a gain of approximately 23 dB.

The amplifier output is coupled through two broadband ceramic filters (FL2 and FL3) and applied to Mixer U2. The mixer is a high level passive switch with a loss of approximately 6.5 dB.

First Mixer And IF

The local oscillator (LO) injection for the mixer is generated by the receiver synthesizer located on the exciter board. The 826-831 MHz LO signal from the exciter is applied to the receiver board at J4, where it is amplified to approximately

The 70 MHZ mixer output is amplified by 1st IF Amplifier U4. Two 70 MHz crystal filters, FL5 and FL6, provide the 1st IF filtering. Adjustable coils L7 and L9 provide matching for proper response of IF filter FL6.

The high stability 17.6125 MHz reference frequency from the master oscillator is applied to the receiver board at J2. This reference frequency is buffered by Q1, and applied to phase detector U10.

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100 milliwatts by RF Amp U3, filtered by FL4, and applied to the 1st mixer.

Synthesizer

A synthesizer circuit located on the receiver board provides the 2nd LO frequency of 70.450 MHZ. The synthesizer consists of counter U9, phase detector U10, DC amp U11, VCO FET Q3, RF buffer amplifiers Q1, Q2 and Q4.

VCO Q3 operates at 70.450 MHz. The circuit is tuned by L11. The output of the VCO is coupled through buffer amp Q4 and RF amp Q2, and applied to the divide-by-four counter, U9. The counter output is applied to phase detector U10, whose output is applied to DC amplifier U11. Feedback for the loop control voltage is developed across R7.

The 70.450 MHz output is coupled through C40 from the collector of Q4 to pin 4 of audio IC, U6, , where it is mixed with the 70 MHZ 1st IF input to derive the 455 kHz 2nd IF.

Second Mixer, IF & Audio

Integrated circuit (IC) U6 contains the 2nd mixer, 2nd IF amplifier and mixer stages, the audio detector and audio amplifiers.

The 70 MHz 1st IF output of FL6 is applied to U6-1. The 70.450 MHz 2nd LO signal is applied to the 2nd mixer at U6-4 to derive the 450 kHz 2nd IF signal. The 450 kHz IF is filtered by ceramic filters FL7 and FL8. The audio component of the 2nd IF is demodulated by the quadrature detector circuit in U6. Network Z1 provides the required 90° phase shift of the 450 kHz signal. The de-modulated audio from U6-8 is coupled through buffer Q5 and applied to audio output jack J3-3.

RSSI Voltage

The Received Signal Sensitivity Indication (RSSI) is a DC level that is proportional to the receiver RF input signal level to the receiver. This voltage can be measured at J3-4.



Supply Voltage

The receiver is supplied by a regulated 10 volts from the system board. However, the more critical circuits are supplied by voltage regulators U5, U7 and U8 for stability and isolation.

Regulated 10 volts from the system board is used to supply RF amplifier U1, IF amp U4, VCO transistor Q3, and RF buffer Q4. Regulator U5 provides the 5-volt supply for audio IC, U6, and 5-volt regulator U7 supplies counter U9, Phase detector U10, and RF amps Q1 and Q2. The 8-volt regulator (U8) provides power for RF amp U3 and audio buffer Q5.

AUDIO BOARD

Figure 1 - Receiver Board Block Diagram

Audio board 19D902181G1 consists of a preamplifier circuit, squelch detector, audio IC and audio PA circuit. The audio board is connected to the system board through P904. The discriminator output is connected through J601-3 on the audio Figure 2.

Audio Preamplifier

Discriminator audio from J602-3 is coupled through Audio Level Adjust R608 to the preamplifier circuit. The preamp consists of Q601, Q602, Q605 and associated circuitry, and provides 26 dB of gain. The amplified output is connected to the squelch and audio hybrid ICs through the arm of the VOL and SQ controls on the exciter-receiver door assembly.

Receiver Audio



Figure 2 - Block Diagram; Audio Board 19D902181G1

board. Power is supplied from a regulated 10 volts from the system board. A Block Diagram Of the audio board is shown in

The audio circuitry consists of a three-stage, quad integrated circuit (U602-A, U602-C and U602-D). The three stages provide a standard EIA Channel Guard tone reject filter, a receiver de-emphasis circuit, and the low level audio driver circuitry.

Audio from the pre-amplifier circuit is coupled through the VOLUME control to VOLUME arm (P904-13). The audio at P904-13 is applied to CG tone reject filter U602-C, U602-D and associated circuitry to remove any low frequency signal. The filter output is then applied to a 6-dB per octave de-emphasis/audio driver circuit (U602-A). The audio driver output is AC-coupled to the Class AB audio PA integrated circuit, U604-1.

The PA output is coupled through C633 to provide rated power to the 8-ohm speaker. Feedback from U604-3 is coupled through R652 and C630 to determine the gain of the audio power amplifier. Capacitor C634 is connected across the output to protect U604 from a "no load" or open circuit condition.

Receiver Squelch

Audio Switches

U606 is a dual section, audio switching IC that acts as two form "C" (N.O.- N.C.) contacts. The switch states are controlled by the inputs at U606A-10 and U606B-11. Both of the inputs are activated by the receiver SQ DISABLE function.

When the receiver is squelched, pin 11 of U606-A is near A-. This turns off the entire audio circuit to eliminate noise. Pin 1 of U606-B is connected to the system board through P904-7 (RX MUTE). This allows the receiver audio to be disabled by the Channel Guard option when used.

Pin 2 of U606-10 is connected to the system board through P904-6 (SQ DISABLE) so that the receiver audio stages can be activated for an alert tone output whenever the Carrier Controlled Timer or other options are used.

Squelch ICs

The receiver squelch circuit consists of noise amplifier U602B, active noise filter U601C and U601D, noise rectifier U601B, DC amp U601A, and level detector U603D. In addition, the squelch circuit contains the Receiver Unsquelched Sensor (RUS) switch U603B, Carrier Activity Sensor (CAS) switch U603A, and the RX MUTE switch U603C. The RX MUTE switch controls the audio path to audio IC U604 through U606.

Noise Amp, Filter & Level Detector

Noise from the limiter/detector at P904-10 is coupled to the noise amplifier U602B through the SQUELCH control, and then applied to the active noise filter (U601C and U601D). The active filter provides the gain and selectivity necessary to distinguish between noise and audio. The filter output at U601D-14 drives the level detector circuit to provide the squelch switching functions. Potentiometer R622 adjusts the noise level for the proper squelch operation.

Squelch Switches

Level detector U603D controls two of the switched squelch outputs. The first output controls the RX MUTE switch (U603C), and the second output controls the CAS switch (U603A). The RUS switch (U603B) is also controlled by the RX MUTE signal.

The squelch input to the level detector is at U603D-10. U603D-11 is referenced to 4 Volts from voltage divider R640 and R641. When the receiver is squelched, the input at U603D-10 is near 3 Volts, and the output at pin 13 is approximately 10 Volts. This keeps the output of receiver audio stages turned off, muting the audio. The level detector output is connected to its input through R639, providing a hysteresis loop in the squelch circuit to prevent squelch closing on weak signals.

When the receiver is quieted by an on-frequency signal (receiver unsquelches), the voltage at U603D-10 rises to approximately 5 Volts DC, and the output at pin 14 drops to near 0 volts. This turns on the audio stages and sound is heard at the speaker.

RUS Switch (Receiver Unsquelched Sensor)

When the receiver is unsquelched, the output of the level detector (U603D-13) goes low. The low turns off U603C, causing U603B-1 to go high (approximately 10 Vdc), turning on RUS switch U603B. The RUS output at U603B-1 is also connected to the system board through P904-8 for use in special applications.

CAS Switch (Carrier Activity Sensor)

Level detector U603D also drives CAS switch U603A. When the receiver unsquelches, the voltage at U603A-2 rises to approximately 10 volts. This voltage is connected to the system board through P904-9 where it is used to activated such options as the Channel Busy light, Carrier Control Timer, and Carrier Operated Relay.

AUDIO BOARD

Audio board 19D902093G1 consists of a preamplifier circuit, squelch detector, audio IC and audio PA circuit. The audio board is connected to the system board through P904. The discriminator output is connected through J601-3 on the audio board. Power is supplied from a regulated 10 volts from the system board. A Block Diagram of the audio board is shown in Figure 3.

Audio Preamplifier

Discriminator audio from J602-3 is coupled through Audio Level Adjust R608 to the preamplifier circuit. The preamp consists of Q601, Q602, Q605 and associated circuitry, and provides 26 dB of gain. The amplified output is connected to the squelch and audio hybrid ICs through the arm of the VOL and SQ controls on the exciter-receiver door assembly.

Audio IC

Hybrid audio IC U604 contains a standard EIA Channel Guard tone reject filter, a receiver de-emphasis circuit, and the low level audio drivers.

Audio from the VOLUME control arm is coupled through P904-13 to pin 4 of the audio IC. The audio at U604-4 is applied to a Channel Guard tone reject filter to remove any low level signal. The filter output is then applied to a 6-dB per octave de-emphasis circuit. The de-emphasized output is coupled through C635 to the differential audio driver circuit.

The driver output is DC-coupled to the base of push-pull audio PA amplifiers Q603 and Q604. The PA output is coupled



Figure 3 - Block Diagram; Audio Board 19D902093G1

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through audio transformer T601 to provide rated power to the 8-ohm speaker. Feedback from windings T601-3 and -4 determine the gain of the differential audio driver in U604. Resistor R619 and capacitor C637 in the transformer secondary protect the PA transistors from a "no load" or open circuit conditions.

When the receiver is squelched, U604-1 drops to near A-. This turns off the entire audio circuit to eliminate current drain. Pin 1 of U604 is also connected to the system board through P904-7 (RX MUTE). This disables the receiver audio whenever the Channel Guard option is used.

Pin 2 of U604 is connected to the system board through P904-6 (SQ DISABLE) so that the receiver audio stages can be activated for an alert tone output whenever the Carrier Controlled Timer or other options are used.

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Squelch IC

Squelch hybrid U603 contains the noise amplifier, active noise filter, detector, slow and fast squelch circuits, the Receiver Unsquelched Sensor (RUS), and the Carrier Activity Sensor (CAS) switch.

Noise from the quadrature detector is coupled through the audio preamp to the SQUELCH control, and then through P904-10 to pins 1 and 2 on Squelch IC U603. The input is then applied to the noise amplifier and active filter to provide the gain and selectivity necessary to distinguish between noise and audio. The filter output is applied to external noise amplifier U601 which provides the extra noise gain required for narrow band signals. The amplifier output at U601-1 drives the active detector circuits in U603 to provide the squelch switching functions.

Thermistor RT601 keeps the input to the active detector constant over wide variations in temperature. R622 is used to set the noise level for proper squelch operation.

With a signal below the 20 dB quieting level, the slow squelch circuit provides a conventional (200 millisecond) slow squelch operation to prevent rapid squelch opening and closing in weak signal areas. Service Note: In station applications, the fast squelch function is disabled by removing C360.

RX Mute

The squelch RX MUTE output at U603-7 is connected to pin 1 of audio IC, U604. When the receiver is squelched, the output at U603-7 is near A-. This keeps the differential audio driver turned off, muting the receiver.

When the receiver is quieted by an on-frequency signal (receiver unsquelches), the voltage at U603-7 rises to approximately 10 volts. This turns on the audio driver and audio PA so that sound is heard at the speaker.

RUS Switch (Receiver Unsquelched Sensor)

With the receiver unsquelched, the output of the squelch switch in U603 turns on the RUS switch. Th RUS switch output is connected to the noise amplifier stage, providing the hysteresis loop in the squelch circuit. The RUS output (when unsquelched) increases the gain of the noise amp, ppreventing squelch closing on weak signals. The RUS output at U603-8 is also connected to the system board through P904-8 for use in special applications.

CAS Switch (Carrier Activity Sensor)

The squelch in U603 also drives the CAS switch in the IC. When the receiver unsquelches, the voltage at U603-6 rises to approximately 10 volts This voltage is connected to the system board through P904-9 where it is used to activated such options as the Channel Busy light, Carrier Control Timer, and Carrier Operated Relay.

MAINTENANCE

SERVICING

To gain access to the receiver for servicing, refer to the following procedure (see Figure 4).

To service the receiver from the top:

- 1. Turn the two latching knobs "A" counterclockwise to unlatch the radio housing door as shown in Figure 4.
- 2. Swing the radio housing down as shown in Figure 5 and remove the top cover.

To service the receiver from the bottom:

- 1. Turn the two latching knobs "A" counterclockwise to unlatch the radio housing and swing the housing down as shown.
- 2. Remove the top cover. Then grasp the receiver handle "B" and swing the housing up for access to the bottom of the receiver.



Remove the two RF cables connecting the receiver and exciter before raising the receiver housing as directed in Step 2.

There are only four controls that require adjustment during system adjustment. Refer to the system adjustment procedure contained in GETC Maintenance Manual, LBI-38164.

TROUBLESHOOTING

Both the Schematic and Outline diagrams contain troubleshooting information to assist in servicing the receiver. This service information includes voltage and gain readings, power levels and signal flow information. Refer to these diagrams when troubleshooting the receiver (see Table of Contents).

ADJUSTMENTS

The receiver has no adjustments for "peaking" up receiver performance. If some adjustment is required as a result of component replacement or other maintenance, refer to the Adjustment Procedure listed in the Table of Contents.



B

Figure 3 - Access To Knobs Securing Door

Figure 4 - Access To Receiver (Top and Bottom)



ADJUSTMENT PROCEDURE

ADJUSTMENT PROCEDURE

The receiver has no field adjustments for peaking up performance. However, should it become necessary to replace components at the customer location, the following adjustments may be required.

Calibration of the 70.45 MHz 2nd L.O.(L11):

- 1. Remove the top cover of the receiver, and then disconnect the 17.6125 MHz reference signal from J2.
- 2. Measure for 70.45 MHz ±50 kHz at J5. If necessary, carfefully adjust L11 to obtain 70.45 MHz ±50 kHz (see CAUTION below).

CAUTION

The tuning slug in L11 is very fragile. Do NOT use a hard material tuning tool such as metal or ceramic to tune the coil. If it should become necessary to tune the L11, it is suggested that a tuning tool be constructed out of a round toothpick or equivalent plastic tool that has one end fashioned into a flat tuning edge.

Receiver Board

Calibration of the 70 MHz IF Filter (FL6):

- 1. Remove the receiver top cover and apply an on-frequency RF signal to antenna input jack, J1.
- 2. Adjust the input signal level to -100 dBm and peak L7 and L9 for a reading of approximately 3.0 volts DC at J3-4. (Refer to figure 5 for typical RF levels vs. RSSI voltages.)

CAUTION

The tuning slugs in L7 and L9 are very fragile. Do not use a hard material tuning tool such as metal or ceramic. If it becomes necessary to tune L7 and L9, it is suggested that a tuning tool be constructed out of a round toothpick or equivalent plastic tool that has one end fashioned into a flat tuning edge.



Figure 5 - Typical RF Levels vs. RSSI Voltages

Calibration OF Quadrature Detector Z1:

- 1. Remove the receiver top cover. Then apply a modulated RF signal to antenna jack J1.
- 2. Adjust the RF generator for -50 dBm with 1 kHz tone at 1.5 kHz modulation.
- 3. Adjust Z1 for maximum audio at J3-3 (200 mV rms minimum). Then adjust Z1 counter-clockwise until the audio level drops 1 dB.

Audio Board

System Audio Level Adjust (R608):

- 1. Apply a -50 dBm RF signal with 1 kHz at the receiver input.
- 2. Adjust R608 for a reading of 1 volt RMS at P904-11 (Volume-Squelch High).

Squelch (Noise) Calibration:

- 1. Turn the SQUELCH control on the exciter-receiver door fully clockwise. Then turn the control counterclockwise approximately one third of the way.
- 2. Adjust R622 until the voltage reading at P904-7 (RX MUTE) just drops to near zero volts. Then readjust the SQUELCH control for critical squelch.

RC-7058 MADE FROM 19D902093

RECEIVER BOARD

ADJUSTMENT PROCEDURE

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Audio Board

(19D902181, Sh. 1, Rev. 0)

RC-7057 MADE FROM 19D902083 REV. 3

RECEIVER BOARD 19D902083G1

6

IN - LINE

TOP VIEW

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

FOR Q4 & Q5

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[o

+ L17 +

+2+3+4 FL7 ---

LEAD IDENTIFICATION

- TOP VIEW NOTE: CASE SHAPE IS DETERMINING

IN - LINE

- FACTOR FOR LEAD IDENTIFICATION.

TOP VIEW

(1

FL5

L3

- L4 -

(19D902083, Sh. 1, Rev. 3) (19A705498, Sh. 1, Rev. 3)

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+

+ FL4 +

+

+ L10

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and a

U4

(ce3)

- [11] -+

++++₉+

FL6 (+++)

+r₂ 9+

§+++

+ 94

L12

+ + CR1 + CR1 +

(+)⁸

+ RT1 -

1 U11

+ L16 -

+ FL3

LEAD IDENTIFICATION

FOR Q3

IN - LINE

TOP VIEW

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

EL A1

⁹+ ²+ ¹+

U2

₉+ +

5

E

+ 12+

A

+ FL2 +

đ

L15

-

A

+ FL1 +

(†)e

₹ ↓ J2

\$∰ J1

LEAD IDENTIFICATION

FOR U5 & U7

IN - LINE

TOP VIEW

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

FLAT

.3

OUTLINE DIAGRAM

3

R24

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□8

APPLY SILICONE GREASE BETWEEN U8 AND BOARD (ITEM 2) PER PROCESS 19A701431 (P6A-EA11). THE FOLLOWING ITEMS ARE MOS DEVICES REQUIRING

U8 (REF)

.62

.72 _____

FORMING DIMENSIONS

FOR U8 LEADS

SPECIAL CARE PER 19A701294, Q3

.240

C50

R18 🗖

R19 🗖

🛛 R4 🗖

8

R21

C32 R5

8

R17

R16

C46

.

□2

2

C45

VIEW FROM SOLDER SIDE

3 1

LEAD IDENTIFICATION FOR U1

BOTTOM VIEW

C34

R20

80°

______ ₽_____

C18 C16 C55

_____C54

C15

(19D902083, Sh. 2, Rev. 3)

(19A705498, Sh. 2, Rev. 3)

PIN #1

SECTION A - A

C17

C33

R1 C39 R12 R12 R14 C41

SCHEMATIC DIAGRAM

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RECEIVER BOARD 19D902083G1

LEAD IDENTIFICATION FOR U607

IN - LINE

TOP VIEW

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

(19D902181, Sh. 1, Rev. 0) (19D902182, Sh. 1&2, Rev. 3)

AUDIO BOARD 19D902181G1

SCHEMATIC DIAGRAM

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AUDIO BOARD 19D902181G1

LEAD IDENTIFICATION FOR Q601, Q602, & Q605

IN - LINE **TOP VIEW** NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

> (19D902093, Sh. 1, Rev. 0) (19A705508, Sh. 1&2, Rev. 0)

AUDIO BOARD 19D902093G1

SCHEMATIC DIAGRAM

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AUDIO BOARD 19D902093G1

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PARTS LIST

PARTS LIST				PART NO. DESCRIPTION			
		900 MHz RECEIVER ASSEMBLY 19090212001 ISSUE 3	C48	191702061P77	Ceramic: 470 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM.		
		1550E 3	C49	19A702052P14	Ceramic: 0.01 uF + or - 10%, 50 VDCW.		
			C50	19A702061P33	Ceramic: 27 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM/C.		
SYMBOL	PART NO	DESCRIPTION	C51	19A702052P14	Ceramic: 0.01 uF + or - 10%, 50 VDCW.		
	TART NO.		C52	19A701534P8	Tantalum: 22 uF + or - 20%, 16 VDCW.		
A1		RECEIVER BOARD	C53	19A701534P5	Tantalum: 2.2 uF, + or -20%, 35 VDCW.		
		19D902083G1	C54 and	19A702052P26	Ceramic: 0.1 uF + or - 10%, 50 VDCW.		
	404 7000 500 5	——————————————————————————————————————	C55 C56	19A702061P75	Ceramic: 390 pF, + or - 5%, 50 VDCW, temp coef		
C1	194702052P5	Tantakumu 40 uE . or 20% 4630CM			0 + or - 30 PPM.		
C2	194701034P7				RECTIFIERS		
C3	194702052P5	Ceramic: F0.00 P1 + 01 - 10%, 50 VDCVV.	CR1 and	19A705547P2	Varactor, sim to Frequency Sources KV3201.		
C4 and C5	194702001049	+ or - 30 PPM.	CR2		——————————————————————————————————————		
C6	19A702061P69	Ceramic: 220 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM/℃.	FL1 thru FL3	19B801524P1	Filter, bandpass: 898.5 MHz		
C7	19A701534P5	Tantalum: 2.2 uF, + or - 20%, 35 VDCW.	FL4	19B801524P2	Filter, bandpass: 828.5 MHz		
C8	19A702052P5	Ceramic: 1000 pF + or - 10%, 50 VDCW.	FL5	19A705548G2	Crystal filer, monolithic.		
C9			FL6	19A705548G1	Crystal filer, monolithic.		
C10	19A702061P13	Ceramic: 10 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM.	FL7 and	19A705580P1	Ceramic filter: 450 KHz		
C11	19A702061P73	Ceramic: 330 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM/C.	FL8				
C12 thru	19A701534P5	Tantalum: 2.2 uF, + or - 20%, 35 VDCW.			JACKS		
C14 C15			J1 and	19A705512P1	Connector, RF SMB Series: sim to AMP No. 221111-1.		
thru C19	19A702052P5	Ceramic: 1000 pF + or - 10%, 50 VDCW.	J2 J3	19A704852P32	Printed wire, two part: 6 contacts, sim to Molex		
C20	19A701534P6	Tantalum: 4.7 uF + or - 20%, 35 VDCW.			22-29-2061.		
C21	19A702052P6	Ceramic: 1500 pF + or - 10%, 50 VDCW.	J4 and	19A705512P1	Connector, RF SMB Series: sim to AMP No. 221111-1.		
* C22	19A702061P45	Ceramic: 47 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM.	JS				
C23	19470205225	Ceramic: 1000 pE + or 10% 50 VDCW			INDUCTORS		
623	19A702061P25	Ceramic: 18 pF + or - 5%, 50 VDCW, temp coef 0 +	L1 and	19A700024P25	Coil, RF: 10.0 uH + or - 10%, 3.70 ohms DC res max.		
624		or - 30 PPM/C.	L2				
C25	19A702061P13	Ceramic: 10 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM.	L3 thru L6	19A700024P1	Coil, RF: 100 nH + or - 10%, 0.08 ohms DC res max, 100 v.		
C26 thru	19A702052P14	Ceramic: 0.01 uF + or - 10%, 50 VDCW.	L7	19B801413P6	Coil.		
C29	401704704704		L8	19A700024P25	Coil, RF: 10.0 uH + or - 10%, 3.70 ohms DC res max.		
C30	19A701534P1	Tantaium: 0.1 uF + of - 20%, 35 VDCW.	19	19B801413P5	Coil		
thru	19A702052P14	Ceramic: 0.01 uF + or - 10%. 50 VDCVV.	110	19A700024P41	Coil RF: 220 uH + or - 10%		
0.05	101700004044		L11	19B801413P6			
C35	19A7U2U61P11	Ceramic: 6.8 pF + or - 0.5 pF, 50 VDC/W, temp coef 0 + or - 60 PPM.	L12	19A700024P25	Coil, RF: 10.0 uH + or - 10%, 3.70 ohms DC res		
C36	19A702061P8	Ceramic: 3.9 pF + or - 0.5 pF, 50 VDCW, temp coef 0 + or - 120 PPM.	L14	19A700024P25	rnax. Coil, RF: 10.0 uH + or - 10%, 3.70 ohms DC res		
C37	19A702061P5	Ceramic: 2.2 pF + or - 0.5 pF, 50 VDCW, temp coef 0 + or - 120 PPM.	L15	19A700024P1	max. Coil, RF: 100 nH + or - 10%, 0.08 ohms DC res		
C38	19A702052P14	Ceramic: 0.01 uF + or - 10%, 50 VDCW.			max, 100 v.		
C39	19A702061P45	Ceramic: 47 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM.	L16	19A700024P2	Coil, RF: 120 nH + or - 10%.		
C40	19A702061P77	Ceramic: 470 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM.	* L17	19A/UUU24P43	сов, на. 530µн т 01 - 10%.		
C41	19A702061P69	Ceramic: 220 pF + or - 5%, 50 VDCW, temp coef 0 + or - 30 PPM/℃.	Q1	19A705531P1			
C42	19A702052P14	Ceramic: 0.01 uF + or - 10%, 50 VDCW.	Q2				
C43	19A701534P5	Tantalum: 2.2 uF, + or - 20%, 35 VDCW.	Q3	19A700060P3	N-Type, field effect; sim to J310.		
C44	19A701534P8	Tantalum: 22 uF + or - 20%, 16 VDCW.	Q4	19A702503P2	Silicon, NPN.		
C45 and	19A702052P14	Ceramic: 0.01 uF + or - 10%, 50 VDCW.	* Q5	344A3104P1	Silicon: NPN; Darlington		
C46	494799955				RESISTORS		
C47	19A702052P5	Ceramic: 1000 pF + or - 10%, 50 VDCW.	R1	19B800607P560	Metal film: 45 ohms + or - 5%, 200 VDCW, 1/8 w.		
			R2	19B800607P101	Metal film: 100 ohms + or - 5%, 200 VDCW, 1/8 w.		
			R3	19B800607P102	Metal film: 1K ohms + or - 5%, 200 VDCW, 1/8 w.		
			1				
^ COMPON	ENTS ADDED, DI	ELETED OR CHANGED BY PRODUCTION CHANGES	5∟	L			

YMBOL	PART NO.	DESCRIPTION				
R4	1088006070422	Matalfilm - 43K above				
N4 D5	19000007P12J	metal film: 12K onms + of - 5%, 200 VDCW, 1/8 W.				
R6	198800607273	Metal film: 27K onms + or - 5%, 200 VDCW, 1/8 W.				
P7	190000070102	Metal film: 1K onms + or - 5%, 200 VDCVV, 1/8 W.				
thru R9	19000079103	metarium: 10K onms + or - 5%, 200 VDCVV, 1/8 W.				
R10	19B800607P221	Metal film: 220 ohms + or - 5%, 200 VDCW, 1/8 w.				
R11	198800607P682	Metal film: 6.8K ohms + or - 5%, 200 VDCW, 1/8 w.				
R12	19B800607P392	Metal film: 3.9K ohms + or - 5%, 200 VDCW, 1/8 w.				
R13 and R14	198800607P681	Metal film: 680 ohms + or - 5%, 200 VDCW, 1/8 w.				
R15	19B800607P472	Metal film: 4.7K ohms + or - 5%, 200 VDCW, 1/8 w.				
R16	19B800607P563	Metal film: 56K ohms + or - 5%, 200 VDCW, 1/8 w.				
R17 and R18	19B800607P331	Metal film: 330 ohms + or - 5%, 200 VDCW, 1/8 w.				
R19	19B800607P223	Metal film; 22K ohms + or - 5%, 200 VDCVV 1/8 w				
R20	1988006072560	Metal film: 56 ohms + or - 5% 200 VDCW 4/2 m				
R21	19B800607P123	Metal film: 12K ohms + or - 5%, 200 VDCW, 1/8 w				
R22	19B800607P104	Metal film: 100K ohms + or - 5%, 200 VDCW, 1/8 w.				
R23	19B800607P224	Metal film: 220 ohms + or - 5%, 200 VDCW, 1/8 w.				
R24	19B800607P103	Metal film: 10K ohms + or - 5%, 200 VDCW, 1/8 w.				
RT1	19A703813P1					
U1	19A705537P1	— — — — — INTEGRATED CIRCUITS — — — — — — — — — — — — — — Integrated Circuit (MMIC), RF Power Amplifier: sim to Avantek MSA0885.				
U2	19B801025P3	Mixer, balanced (double): sim to Mini-Circuits SRA-173H.				
U3	19A704695P1	Hybrid RF Amplifier: sim to NEC Type MIC-5809L.				
U4	19A705538P1	Amplifier, MMIC.				
U5	19J706031P1	Linear: POSITIVE VOLTAGE REGULATOR.				
U6	19A705535P1	Integrated Circuit, IF System, FM: sim to Signetics SA605N.				
U7	19J706031P1	Linear: POSITIVE VOLTAGE REGULATOR.				
U8	19A134717P3	Linear: 8 Volt Regulator; sim to MC7808CT.				
U9	19A705579P1	Dual D-Type flip flop.				
U10	19A700037P341	Digital: Qual 2 Input Exclusive OR gate; sim to 74LS86.				
U11	19A701789P2	Linear: Dual Op Amp; sim to LM358.				
Z1	19B801415P3					
	1000015					
	19B801531P1	Cover, receiver.				
	19B201074P304	Tap screw, Phillips POZIXDRIV: No. 6-32 x 1/4.				
	19B209382P308	Tap screw, Phillips POZIDRIV: No. 6-32 x 1/2.				
	19A702364P408	Machine Screw: TORX Drive, M3.5 - 0.6 x 8.				
	19A700034P5	Hex nut: No. M3.5 x 0.6.				
	19470003340	Lockwasher, external tooth, M3.5				

PARTS LIST

		PARTS LIST	SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION
		AUDIO BOARD 19090219161 ISSUE 2	R603 and	19A701250P320	Metal film: 15.8K ohms + or .1%, 250 VDCW.	R658	194701250P226	Metal film: 1.82K ohms + or -1%, 1/4 w.
			R604			R659	19A701250P1	Metal film: 10 ohms + or -1%, 1/4 w.
	-		R605	19A701250P251 19A701250P309	Metal film: 3320 onms + or -1%, 1/4 W. Motal film: 12 1K ohms + or -1% 250 VDCW/ 1/4			INTEGRATED CIRCUITS
OVMBOL			1000	1041012001000	W.	U601 and	19A704883P1	OP AMP, QUAD: sim to Motorola MC 3303P.
STIVIBUL	PART NO.	DESCRIPTION	R607	19A701250P157	Metal film: 383 ohms + or -1%, 250 VDCW.	U602		
		CAPACITORS	R608	19B800779P10	Variable: 10K ohms + or -25%, 100 VDCW, .3 watt.	U603	19A134764P1	Linear: (VOLTAGE COMPARATOR).
C601	T644ACP368K	Polyester: .068 uF + or .10%, 50 VDCW.	R609	19A701250P321	Metal film: 16.2K ohms + or -1%, 250 VDCW, 1/4 w.	U604 U606	104700020039	Part of 19822665/G2 Heat Sink Assembly.
C602	Т644АСРЗЗЗК	Polyester: .033 uF + or .10%, 50 VDCW.	R610	19A701250P333	Metal film: 21.5K ohms + or .1%, 250 VDCW, 1/4	U607	19J706031P1	Linear: POSITIVE VOLTAGE REGILATOR.
C603			R611	19A701250P301	w. Metal film: 10K ohms + or -1%, 1/4 w.	0001		
C604	T644ACP368K	Polyester: .068 uF + or .10%, 50 VDCW.	and R612					HEAT SINK ASSEMBLY
C605	T644ACP333K	Polyester: .033 uF + or .10%, 50 VDCW.	R613	19A701250P289	Metal film: 8.25K ohms + or -1%, 250 VDCW, 1/4			19B226657G2
C606 and C607	T644ACP322K	Polyester: .022 uF + or .10%, 50 VDCW.		10170/0500/04	W. Motol film: 224K ohmo - or 4K 250 JDCM: 4 m			Integrated circuits
C600	TEAAACDOOOK	Polyaster: 0022 uE + or 10% 50 VDCM	R615	194701250P434	Metal film: 10K ohms + or 1% 1/4 M	U604	19A705646P1	Integrated circuit.
C609	19A701534P4	Tantalum: 1 uF + or -20%, 35 VDCW.	R616	19A701250P426	Metal film: 182K obms + or -1%, 1/4 w.			MISCELLANEOUS
C610	T644ACP210K	Polvester: .0010 uF + or .10%, 50 VDCW.	R617	19A701250P201	Metal film: 1K ohms + or -1%, 250 VDCW, 1/4 w.		19B226646P1	Heat Sink.
C611	19A701534P8	Tantalum: 22 uF + or -20%, 16 VDCW.	thru R619				4029846P1	Nut, self - locking, steel: thd. size No. 4 - 40,
C612	19A700235P25	Ceramic: 100 pF + or -5%, 50 VDCW.	R620	19A701250P277	Metal film: 6.19K ohms + or -1%, 250 VDCW, 1/4 w.		N407D002D2	(Used with Heat Sink).
C613	19A701225P7	Electrolytic: 100 uF - 10 + 50%, 60 VDCW.	R621	19A701250P301	Metal film: 10K ohms + or -1%, 250 VDCW, 1/4 w.		N107P00000	Heat Sink).
C614 and	T644ACP310K	Polyester: .010 uF + or .10%, 50 VDCW.	R622	19A800779P16	Variable, 100K ohms, + or -25%, 100 VDCW, 3 watt.			
C615			R623	19A701250P289	Metal film: 8.25K ohms + or -1%, 250 VDCW, 1/4 w.			
C616 thru	T644ACP210K	Polyester: .0010 uF + or .10%, 50 VDCW.	R624	19A701250P410	Metal film: 124K ohms + or -1%, 250 VDCW, 1/4 w.		•	
C620			R625	19A701250P281	Metal film: 6.81K ohms + or -1%, 250 VDCW, 1/4 w.			
C621	19A701534P4	Tantalum: 1 uF + or -20%, 35 VDCW.	R626	19A701250P342	Metal film: 26.7K ohms + or -1%, 250 VDCW, 1/4 w.			
C630 thru C632	19A701534P9	Tainaiuni. 47 ur + 01 -20%, 0.3 VDCVV.	R627	19A701250P374	Metal film: 57.6K ohms + or -1%, 250 VDCW, 1/4		PRODU	CTION CHANGES
C633	19A701225P3	Electrolytic: 220 uF, -10 + 50%, 25 VDCW.	R628	19A701250P301	w. Metal film: 10K ohms + or -1%, 250 VDCW, 1/4 w.	Changes Letter," w	n the equipment to impro hich is stamned after the	we performance or to simplify circuits are identified by a "Revision model number of the unit. The revision stamped on the unit includes a
C634	T644ACP410K	Polyester: 0.1 uF + or -10%, 50 VDCW.	thru R632			previous	evisions. Refer to the Pa	rts List for descriptions of parts affected by these revisions.
C635	19A701534P7	Tantalum: 10 uF + or -10%, 50 VDCW.	R633	19A701250P330	Metal film: 20K ohms + or -1%, 250 VDCW, 1/4 w.			
C636	19A701534P9	Tantalum: 47 uF + or -20%, 6.3 VDCW.	R634	19A701250P347	Metal film: 30.1K ohms + or -1%, 250 VDCW, 1/4	REV.	A - <u>Receiver Boa</u>	ard 19D902083G1
C637	19A700004P8	Metallized polyester: 1 uF + or -10%, 63 VDCW.	R635	1007012500366	w. Metal film: 47.5K ohms + or .1% 250 VDCW 1/4 w.		Incorporated	into initial shipment.
C641	19A701534P8	Tantalum: 22 uF + or -20%, 16 VDCW.	R636	19A701250P266	Metal film: 4.75K ohms + or -1%, 250 VDCW, 1/4 w.	REV.	B - Receiver Bo	ard 19D902083G1
		DIODES	R637	19A701250P301	Metal film: 10K ohms + or -1%, 250 VDCW, 1/4 w.		To improve	Test reading at J5. Changed R3.
D601	19A700025P1	Silicon, fast recovery: fwd current 75 mA, 75	R638	19A701250P426	Metal film: 182K ohms + or -1%, 250 VDCW, 1/4 w.		R3 was: 19D80	0607P101: Metal Film, 100 ohms ±5%,
thru D603		PIV; sim to Type 1N4148.	R639	19A701250P320	Metal film: 15.8K ohms + or -1%, 250 VDCW.		1/8 w.	_ , , , , , , , , , , , , , , , , , , ,
		JACKS	R640	19A701250P245	Metal film: 2870 ohms + or -1%, 250 VDCW, 1/4 w.	REV.	C - Receiver Bo	ard 19D902083G1
J602	194704852P32	Drinted wire two parts 6 contacts sim to Moley	R641	19A701250P226	Metal film: 1.82K ohms + or -1%, 1/4 w.		To improve a	audio frequency response for high speed
		22 - 29 - 2061.	R642 and	19A701250P301	Metal film: 10K ohms + or -1%, 1/4 w.		data applicat 194702061P	tions, capacitor C22 was changed to 45 (47 nF) and transistor Q5 was changed
J606	19A701785P1	Contact, electrical: sim to Molex U8 - 50 - 0404.	R043	4047043500304	Motal film: 1K ohme , or 1% 250 VDCM/ 1/1 u		to NPN Darlin	ngton 344A3104P1. Capacitor C56
		INDUCTORS	R044	194701250P201			19A702061P	75 (390 pF) and coil L17 19A700024P43
L601	19A700000P14	Coil, RF: 4.5 uH + or -10%, sim to Jeffers 4411 - 10K.	R646	19A701250P386 19A701250P301	Metal film: 76.8K onms + or -1%, 1/4 w. Metal film: 10K ohms + or -1%, 1/4 w.		(330 µH) Wei	e added between pin 00-8 and Q5 base.
L602	19A700025P41	Coil, RF: 220 uH + or -10%.	and R647				C22 was: 19	A702061P77; 470 pF.
			R648	19A701250P401	Metal film: 100K ohms + or -1%, 1/4 w.		Q5 was: 19/	A700023P2; NPN; SIM to 2N3904.
0004	40004050404	Contact electrical: 7 nine	R649	19A701250P301	Metal film: 10K ohms + or -1%, 1/4 w.			
P904	19B219594P1		R650	19A701250P401	Metal film: 100K ohms + or -1%, 1/4 w.			
		TRANSISTORS	R651 and	19A701250P201	Metal film: 1K ohms + or -1%, 250 VDCW, 1/4 w.			
Q601 thru	19A700023P2	Silicon, NPN: sim to 2N3904.	R652					
Q603			R653	19A701250P289	Metal film: 8.25K ohms + or -1%, 250 VDCW, 1/4 w.			
		RESISTORS	R654	19A701250P121	Metal film: 162 ohms + or -1%, 1/4 w.			
R601	19A701250P251	Metal film: 3320 ohms + or -1%, 1/4 w.	R655	19A701250P366	Metal film: 47.5K ohms + or -1%, 1/4 w.			
R602	19A701250P286	Metal film: 7680 ohms + or -1%, 250 VDCW, 1/4 w.	R656	19A701250P157	Metal film: 383 ohms + or -1%, 250 VDCW.			
			R657	19A701250P266	Metal film: 4.75K ohms + or -1%, 1/4 w.			
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-*COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES \square

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